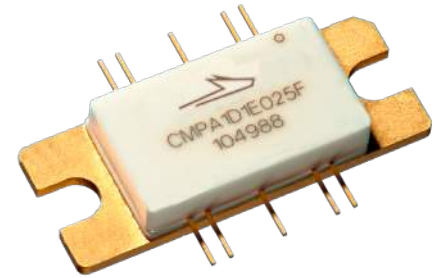


CMPA1D1E025F

25 W, 13.75 - 14.5 GHz, 40 V, Ku-Band GaN MMIC, Power Amplifier



PN: CMPA1D1E025F
Package Type: 440213

Description

WolfSpeed's CMPA1D1E025F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC) on a silicon carbide (SiC) substrate, using a 0.25 μm gate length fabrication process. The Ku-Band 25W MMIC is targeted for commercial Ku-Band satellite communications applications. It offers high gain and superior efficiency while meeting OQPSK linearity required for Satcom applications at 3dB backed off P_{SAT} operations. This Ku-Band MMIC is available in a 10 lead, 25 mm x 9.9 mm metal/ceramic flanged package.

Typical Performance Over 13.75-14.5 GHz ($T_c = 25^\circ\text{C}$)

Parameter	13.75 GHz	14.0 GHz	14.25 GHz	14.5 GHz	Units
Small Signal Gain	24	24.5	24.5	24	dB
Linear Output Power	24	23	21	20	W
Power Gain	21	21	20	20	dB
Power Added Efficiency	22	20	18	18	%

Note:

¹ Measured at -30 dBc, 1.6 MHz from carrier, in the CMPA1D1E025F-AMP under OQPSK modulation, 1.6 Msps, PN23, Alpha Filter = 0.2

Features

- 24 dB Small Signal Gain
- 40 W Typical Pulsed P_{SAT}
- Operation up to 40 V
- 20 W linear power under OQPSK
- Class A/B high gain, high efficiency 50 ohm MMIC Ku-Band high power amplifier

Applications

- Satellite Communication Uplink





Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V_{DSS}	120	V_{DC}	25°C
Gate-source Voltage	V_{GS}	-10, +2		
Power Dissipation	P_{DISS}	94	W	
Storage Temperature	T_{STG}	-55, +150	°C	
Operating Junction Temperature	T_J	225		
Maximum Forward Gate Current	I_{GMAX}	10	mA	25°C
Soldering Temperature ¹	T_S	245	°C	
Screw Torque	τ	40	in-oz	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.5	°C/W	$P_{DISS} = 94 \text{ W}, 85^\circ\text{C}$
Case Operating Temperature	T_C	-40, +85	°C	CW, $P_{DISS} = 94 \text{ W}$

Note: Refer to the Application Note on soldering at wolfspeed.com/rf/document-library

Electrical Characteristics (Frequency = 13.75 GHz to 14.5 GHz unless otherwise stated; $T_C = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics¹						
Gate Threshold	$V_{GS(th)}$	-3.4	-3.0	-2.6	V	$V_{DS} = 10 \text{ V}, I_D = 18.2 \text{ mA}$
Gate Quiescent Voltage	$V_{GS(Q)}$	—	-2.7	—		$V_{DS} = 40 \text{ V}, I_D = 240 \text{ mA}$
Saturated Drain Current ²	I_{DS}	13.1	18.2	—	A	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	V_{BR}	100	—	—	V	$V_{GS} = -8 \text{ V}, I_D = 18.2 \text{ mA}$
RF Characteristics³						
Small Signal Gain	S21	20.9	24	—	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, P_{IN} = -15 \text{ dBm}$
Input Return Loss	S11	—	-7	-6		
Output Return Loss	S22	—				
Output Mismatch Stress	VSWR	—	—	5:1	Ψ	No damage at all phase angles, $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, P_{OUT} = 41 \text{ dBm OQPSK}$

Notes:

¹ Measured on-wafer prior to packaging

² Scaled from PCM data

³ Measured in the CMPA1D1E025F-AMP



Electrical Characteristics Continued (T_c = 25°C)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
RF Characteristics^{1,2,3,4}						
Power Added Efficiency at 13.75 GHz	PAE	14.5	20.5	–	%	V _{DD} = 40 V, I _{DQ} = 240 mA
Power Added Efficiency at 14.5 GHz		12.5	18	–		
Power Gain at 13.75 GHz	G _p	19.25	23	–	dB	
Power Gain at 14.5 GHz		17.75	22	–		
OQPSK Linearity at 13.75 GHz	ACLR	–	-40	-32	dBc	
OQPSK Linearity at 14.5 GHz		–	-38	-30.5		

Notes:

¹ Measured in the CPMA1D1E025F-AMP

² Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2

³ Measured at P_{AVE} = 41 dBm

⁴ Fixture loss de-embedded

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	HBM	TBD	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	TBD	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C



Typical Performance

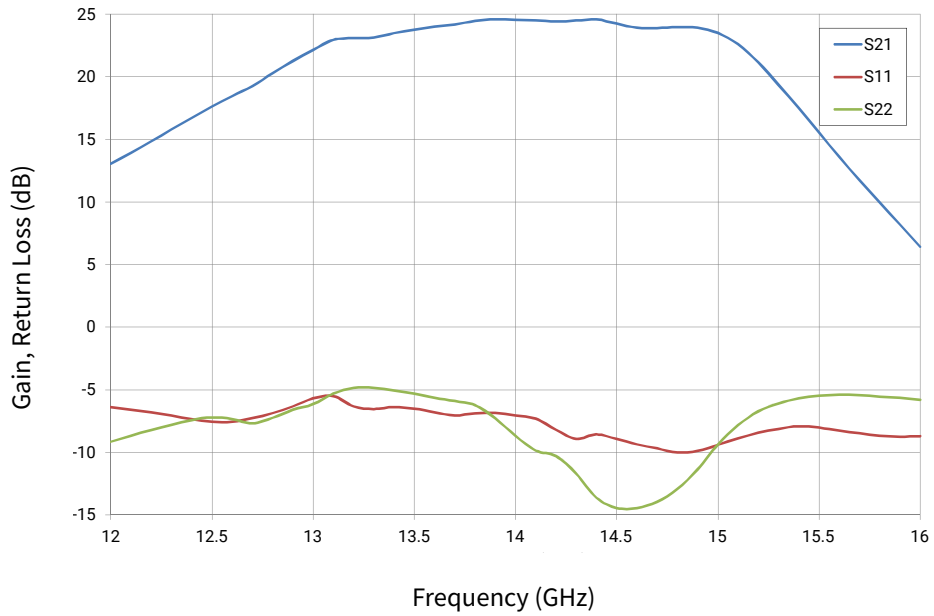


Figure 1. Small Signal S-Parameters CMPA1D1E025F in Test Fixture
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$

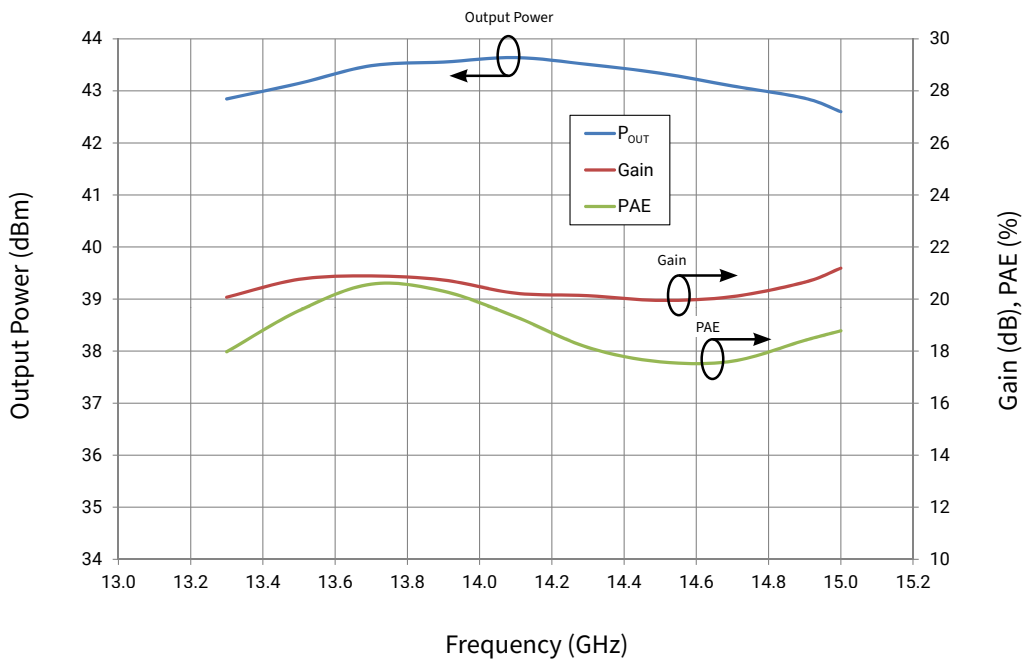


Figure 2. Modulated @ Spectral Regrowth = -30 dBc, 1.6 MHz from Carrier
 1.6 Msps OQPSK Modulation
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

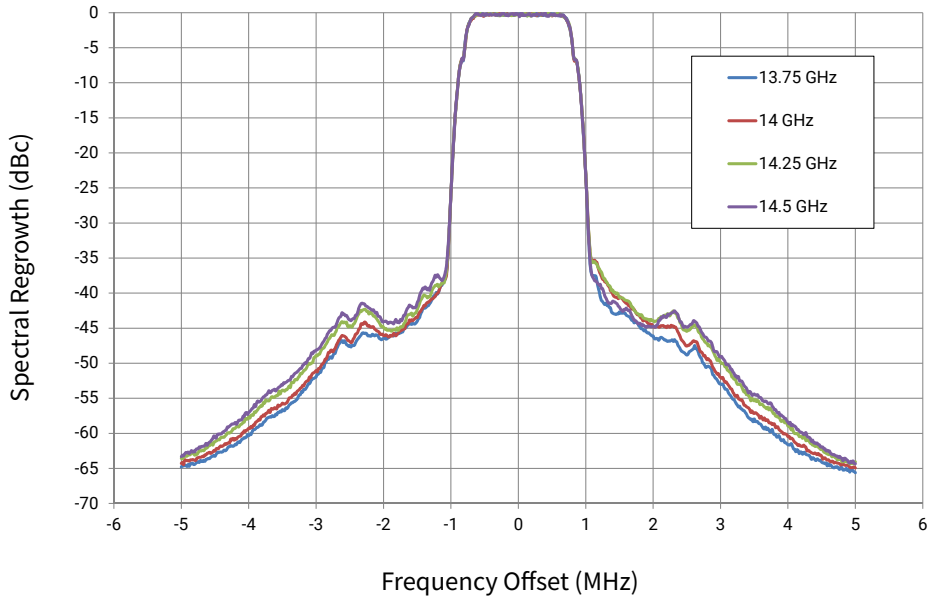


Figure 3. Spectral Mask @ Average Output Power = 41 dBm
 1.6 Msps OQPSK Modulation
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$

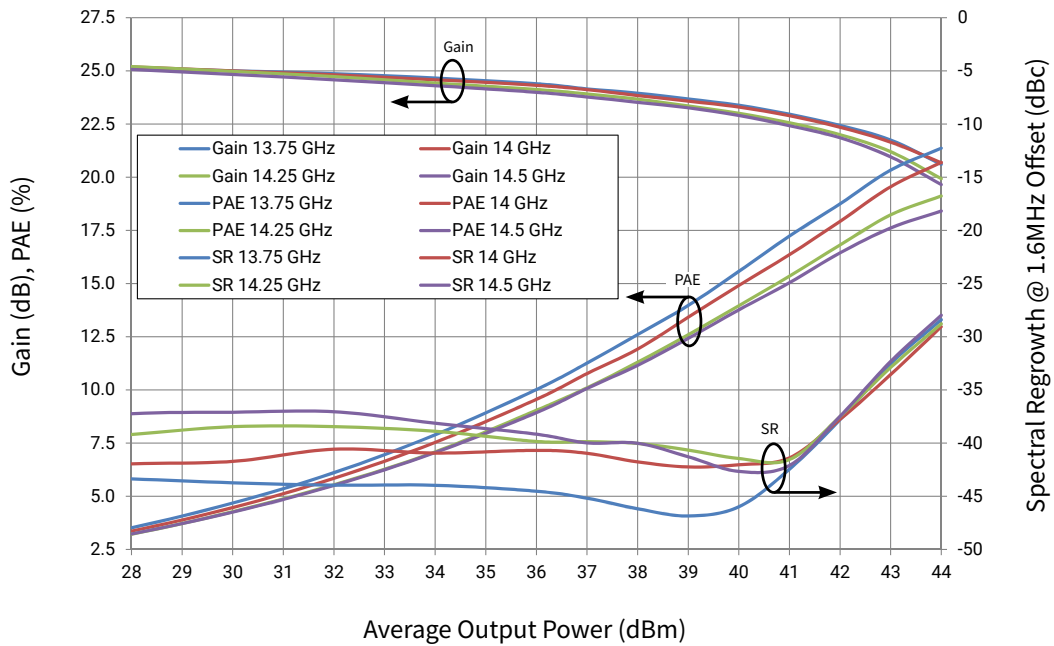


Figure 4. CMPA1D1E025F Modulated Power Sweep
 1.6 Msps OQPSK Modulation
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

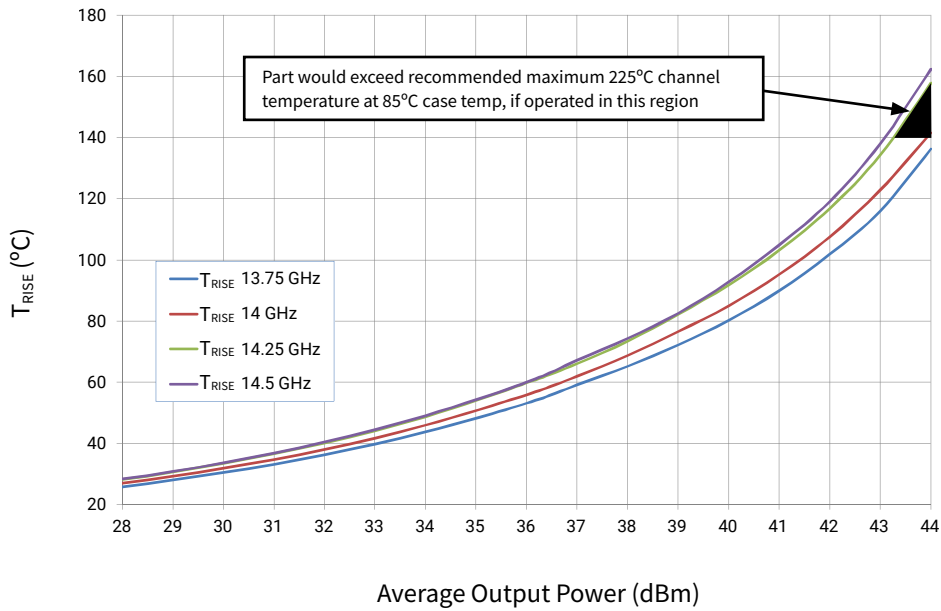


Figure 5. Modulated Power Sweep
 1.6 Msps OQPSK Modulation
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$

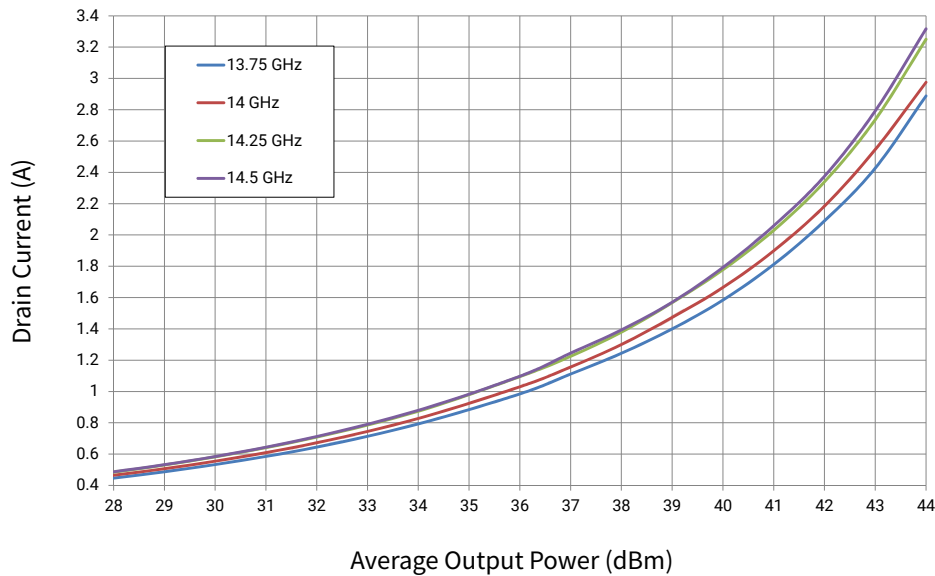


Figure 6. CMPA1D1E025F Modulated Power Sweep
 1.6 Msps OQPSK Modulation
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

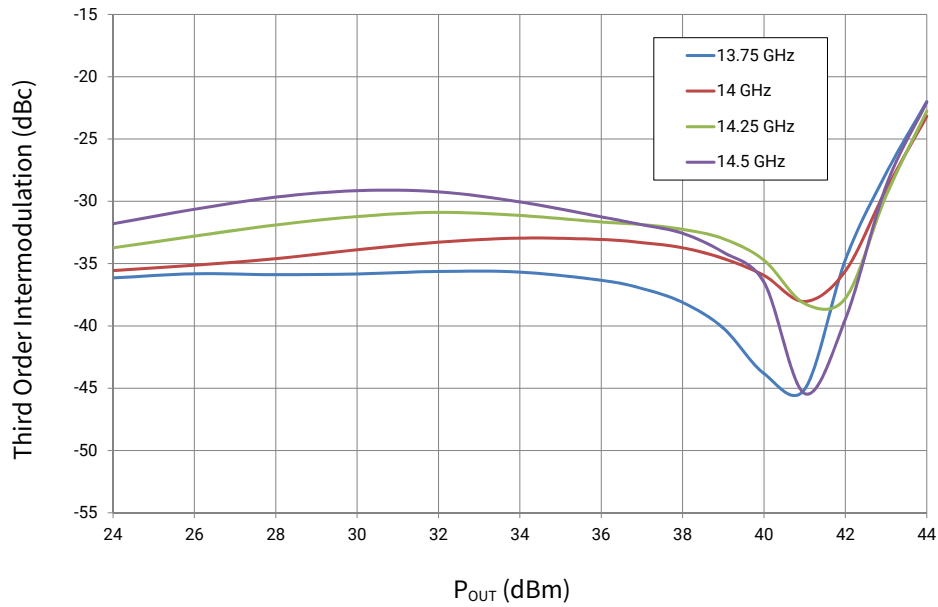


Figure 7. CMPA1D1E025F Two Tone Power Sweep
 IMD3 @ 1 MHz Carrier Spacing
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$

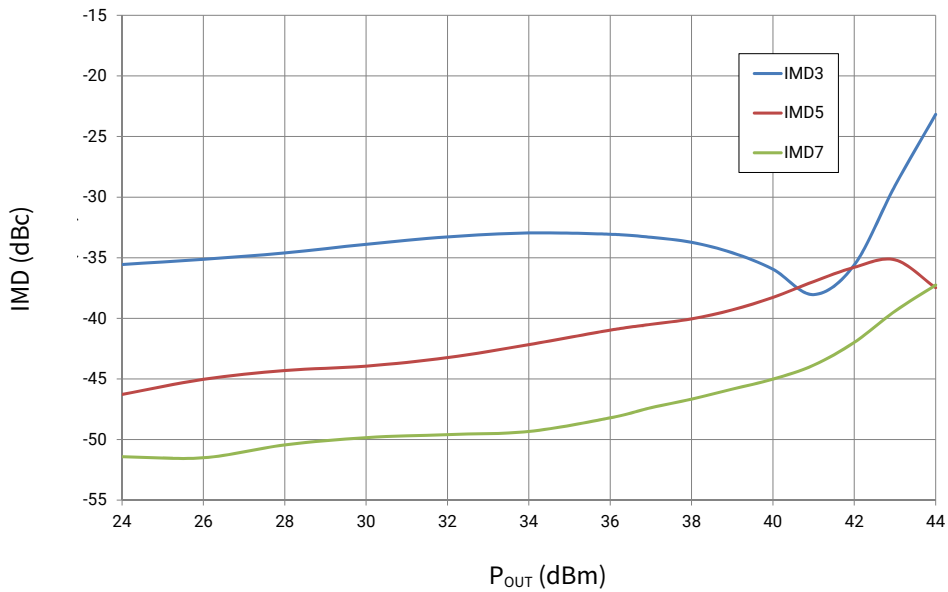


Figure 8. Two Tone Power Sweep
 IMD @ 1 MHz Carrier Spacing, 14 GHz
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

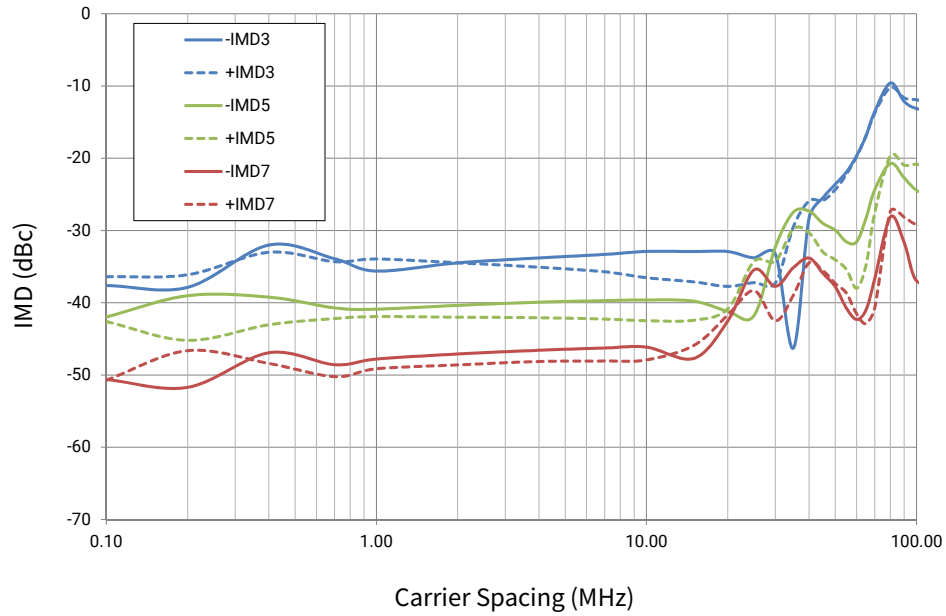


Figure 9. Two Tone Carrier Spacing Sweep @ 38 dBm Average Output Power, 14 GHz
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 1\text{ A}$, $T_{CASE} = 25^\circ\text{C}$

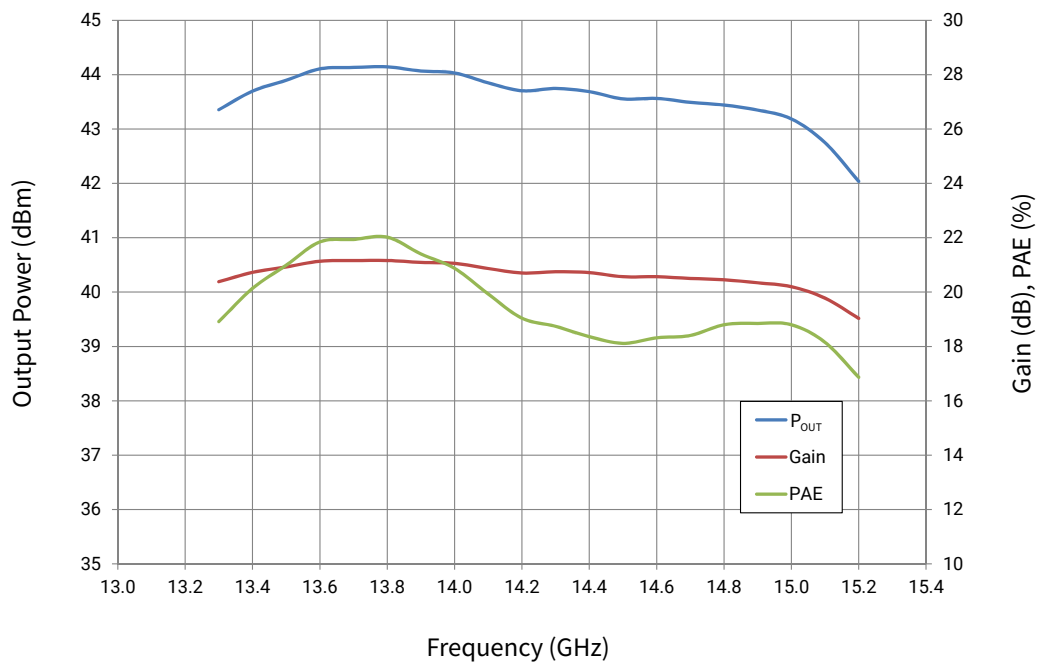


Figure 10. CW vs Frequency @ $P_{IN} = 23\text{ dBm}$
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

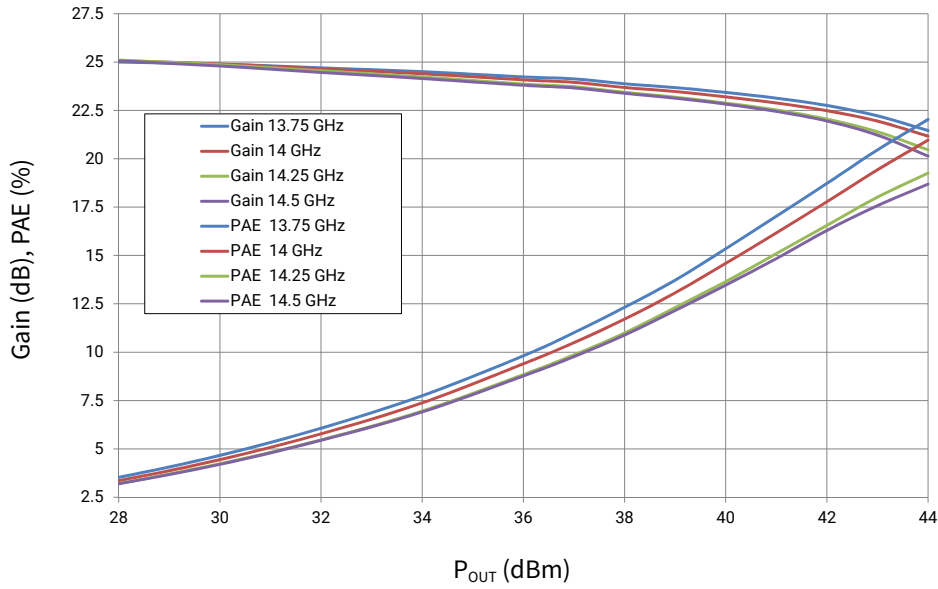


Figure 11. CW Power Sweep CMPA1D1E025F in Test Fixture
 $V_{DD} = 40V, I_{DQ} = 240 \text{ mA}, T_{CASE} = 25^{\circ}C$

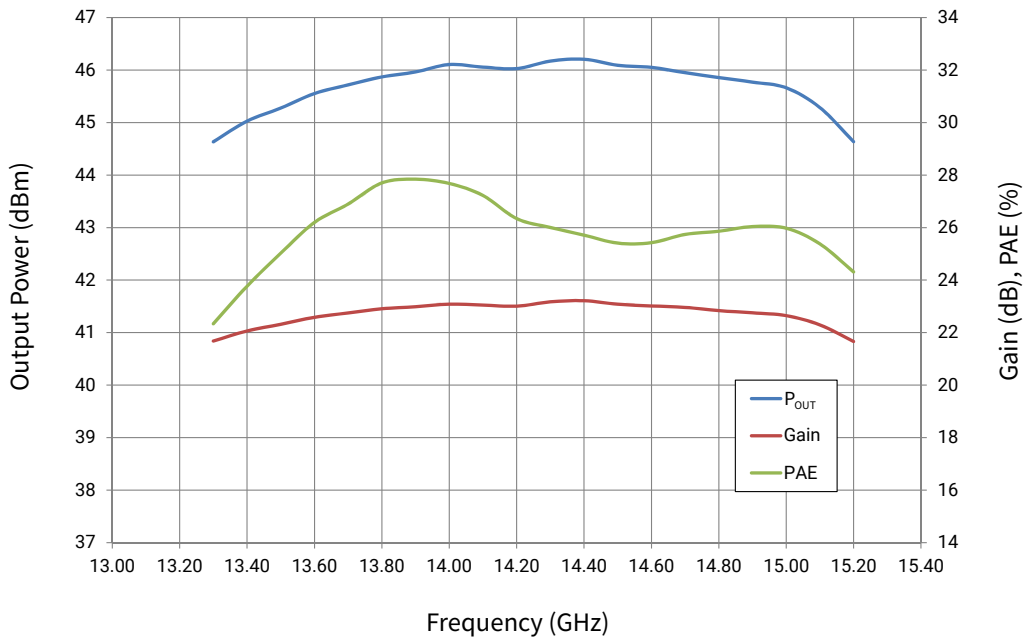


Figure 12. Pulsed vs Frequency @ P_{IN} = 23 dBm CMPA1D1E025F in Test Fixture
 $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, 100\mu\text{s}$ Pulse Width, 10% Duty Cycle, $T_{CASE} = 25^{\circ}C$



Typical Performance

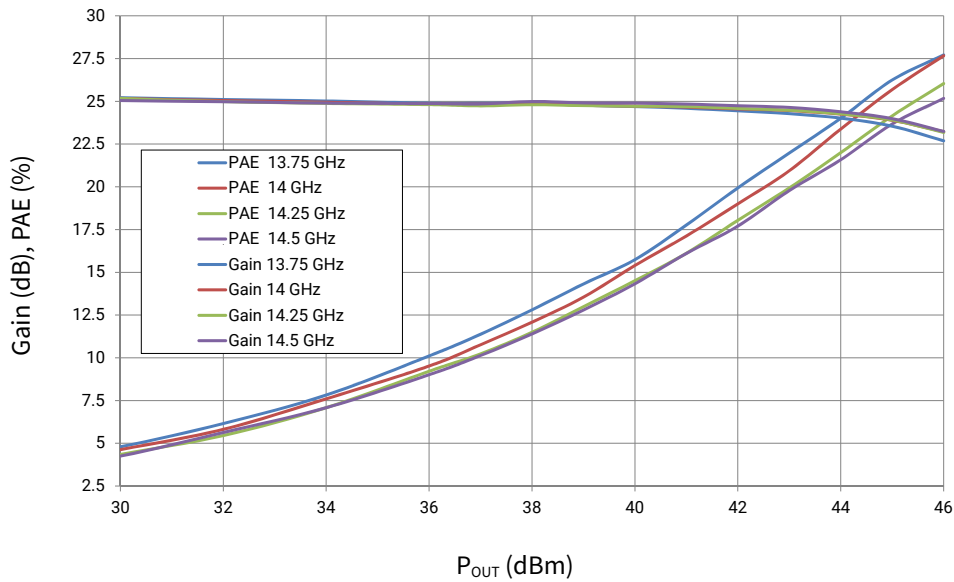


Figure 13. Pulsed Power Sweep CMPA1D1E025F in Test Fixture
 10% Duty, 100μs Pulse Width
 $V_{DD} = 40V$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^{\circ}C$

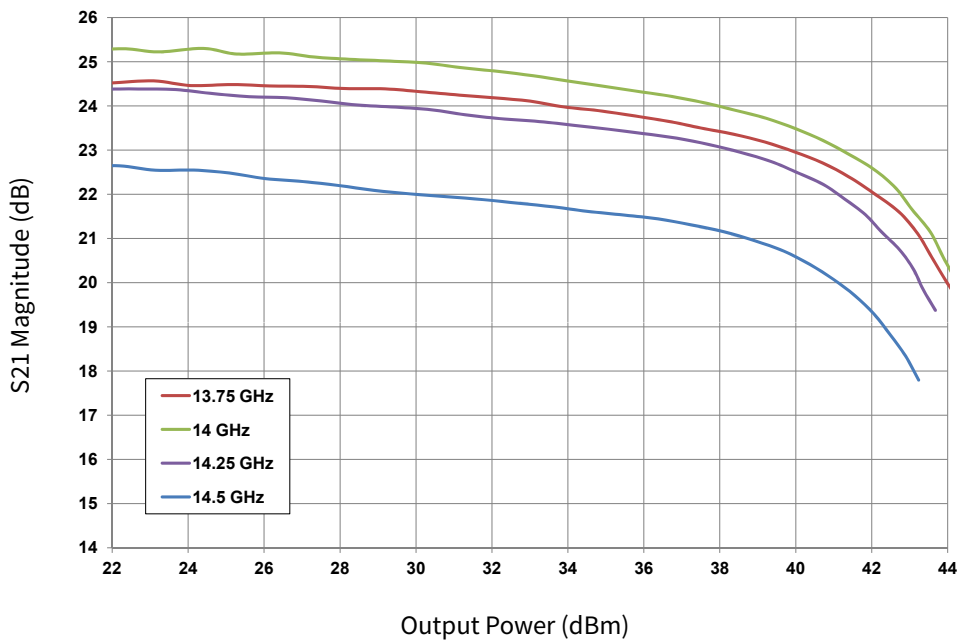


Figure 14. AM-AM
 $V_{DD} = 40\text{ V}$, $I_{DQ} = 240\text{ mA}$, $T_{CASE} = 25^{\circ}C$



Typical Performance

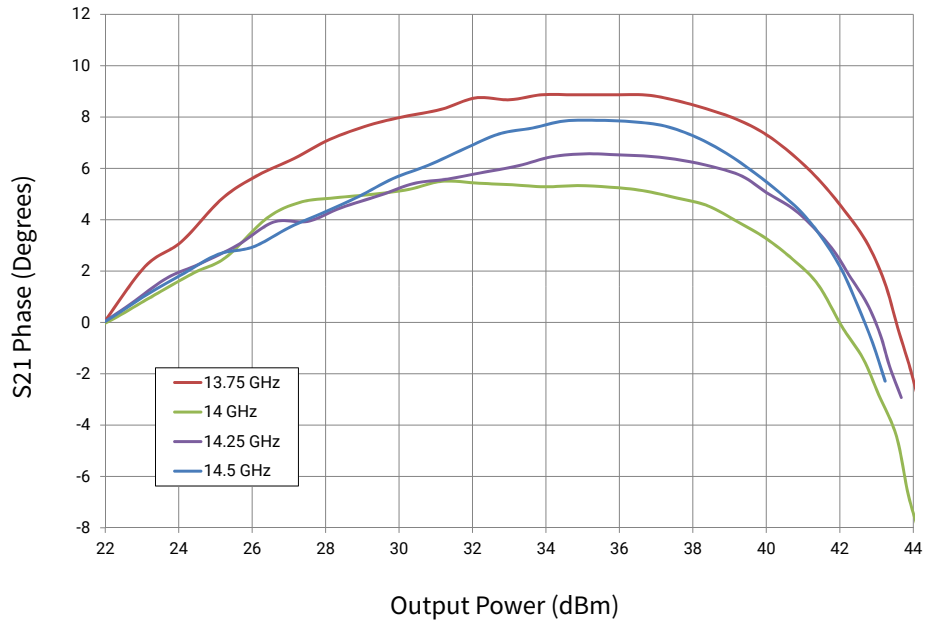


Figure 15. AM-PM
 $V_{DD} = 40V, I_{DQ} = 240\text{ mA}, T_{CASE} = 25^{\circ}C$

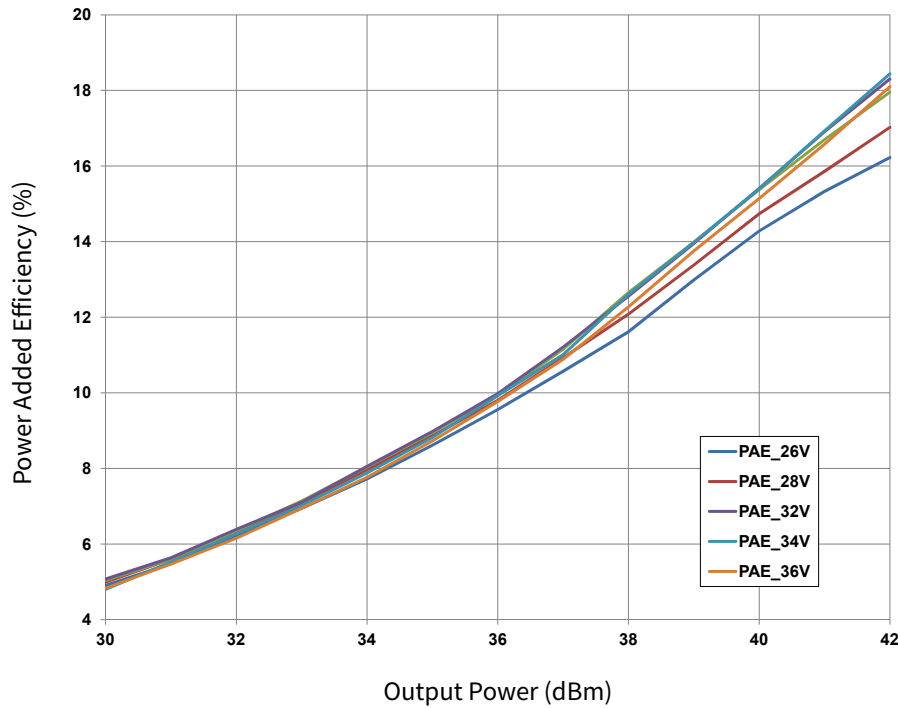


Figure 16. CPM1D1E025F Modulated Power Sweep (PAE and G_P)
 1.6 Msps OQPSK Modulation, Frequency = 14 GHz
 $V_{DD} = 26-36\text{ V}, I_{DQ} = 150\text{ mA}, T_{CASE} = 25^{\circ}C$



Typical Performance

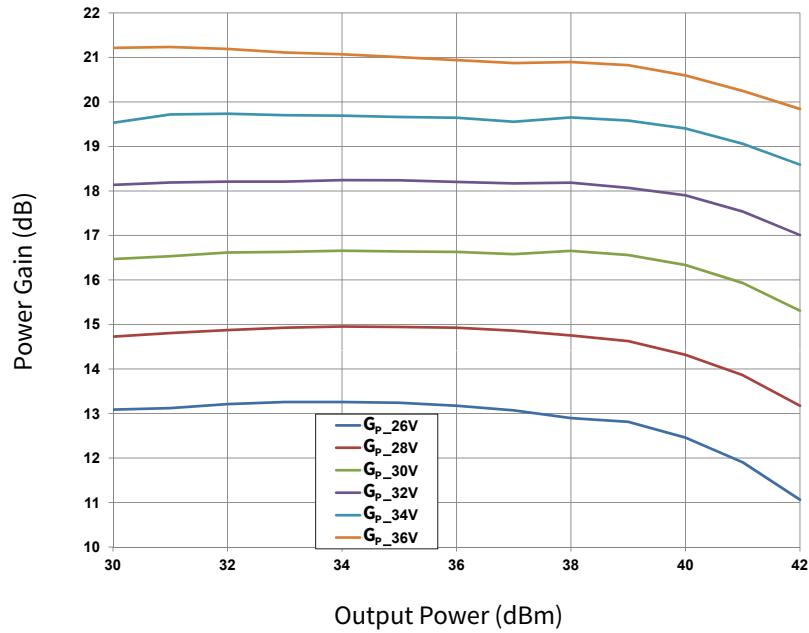


Figure 17. CMPA1D1E025F Modulated Power Sweep (G_p)
 1.6 Msps OQPSK Modulation, Frequency = 14 GHz
 $V_{DD} = 26-36$ V, $I_{DQ} = 150$ mA, $T_{CASE} = 25^\circ\text{C}$

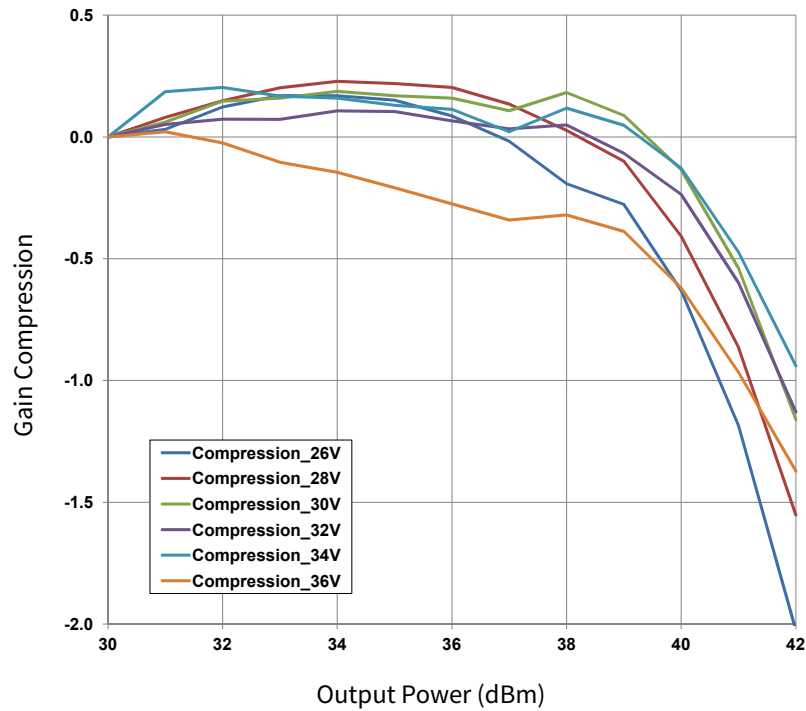
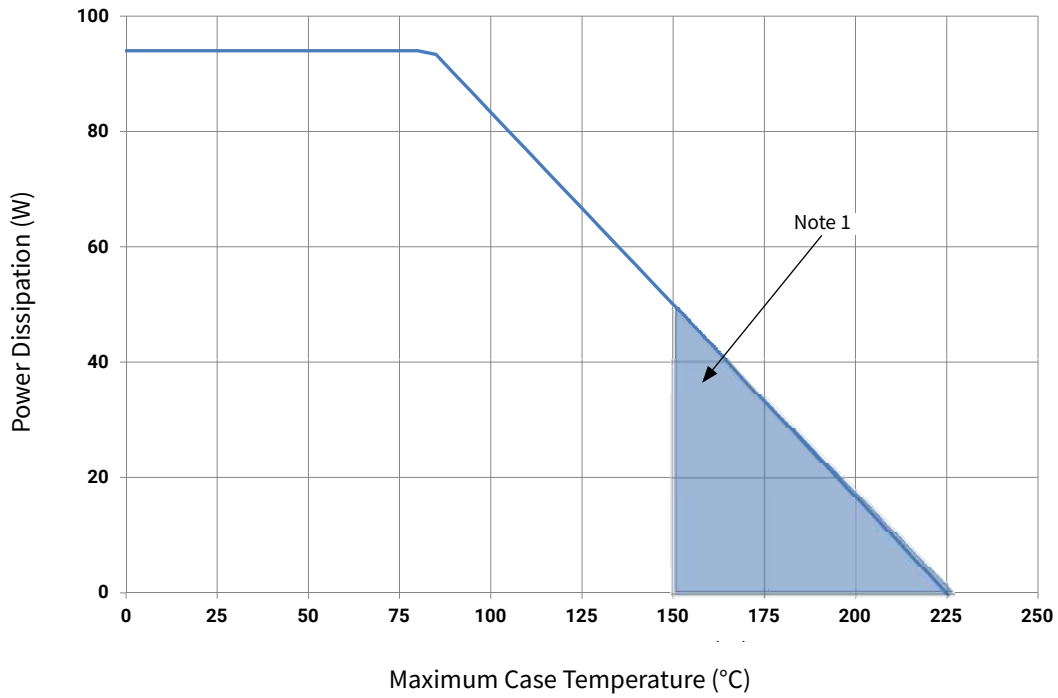


Figure 18. CMPA1D1E025F Modulated Power Sweep (Gain Compression)
 1.6 Msps OQPSK Modulation, Frequency = 14 GHz
 $V_{DD} = 26-36$ V, $I_{DQ} = 150$ mA, $T_{CASE} = 25^\circ\text{C}$



Typical Performance

CMPA1D1E025F Power Dissipation De-rating Curve



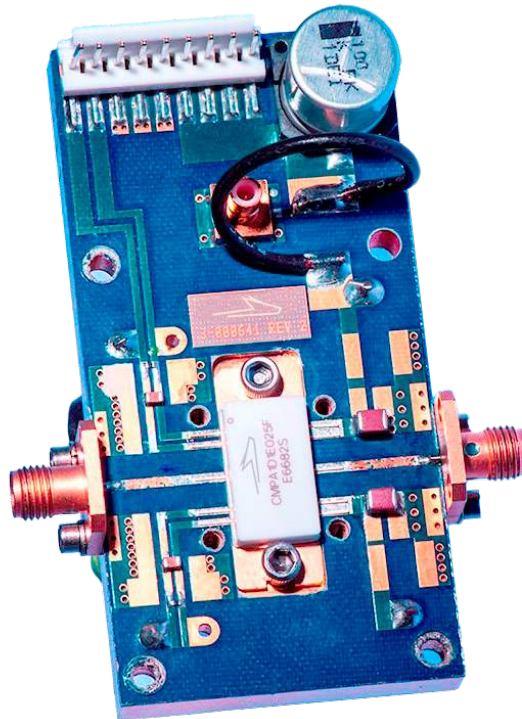
Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2)



CMPA1D1E025F-AMP Demonstration Amplifier Circuit Bill of Materials

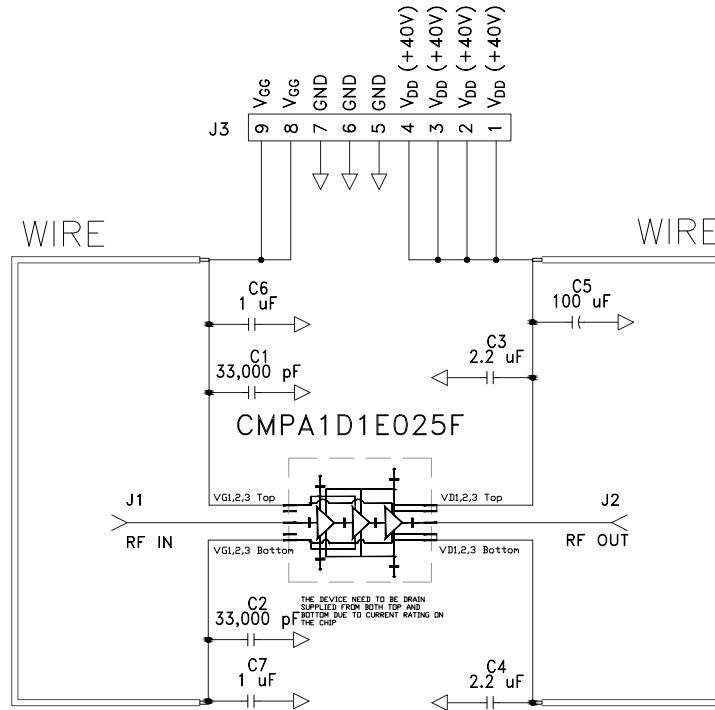
Designator	Description	Qty
C5	CAP ELECT 100 μ F 80V AFK SMD	1
C1, C2	CAP, 33000pF, 0805, 100V, X7R	2
C3, C4	CAP, 2.2 μ F, 100V, 10%, X7R, 1210	2
C6, C7	CAP, 1.0 μ F, 100V, 10%, X7R, 1210	2
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J4	CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED	1
J3	HEADER RT>PLZ .1CEN LK 9POS	1
W1, W2, W3	WIRE, BLACK, 22 AWG	1
	PCB, TEST FIXTURE, TACONICS RF35P, 20 MILS	1
	2-56 SOC HD SCREW 3/16 SS	4
-	#2 SPLIT LOCKWASHER SS	4
Q1	CMPA1D1E025F	1

CMPA1D1E025F-AMP Demonstration Amplifier Circuit

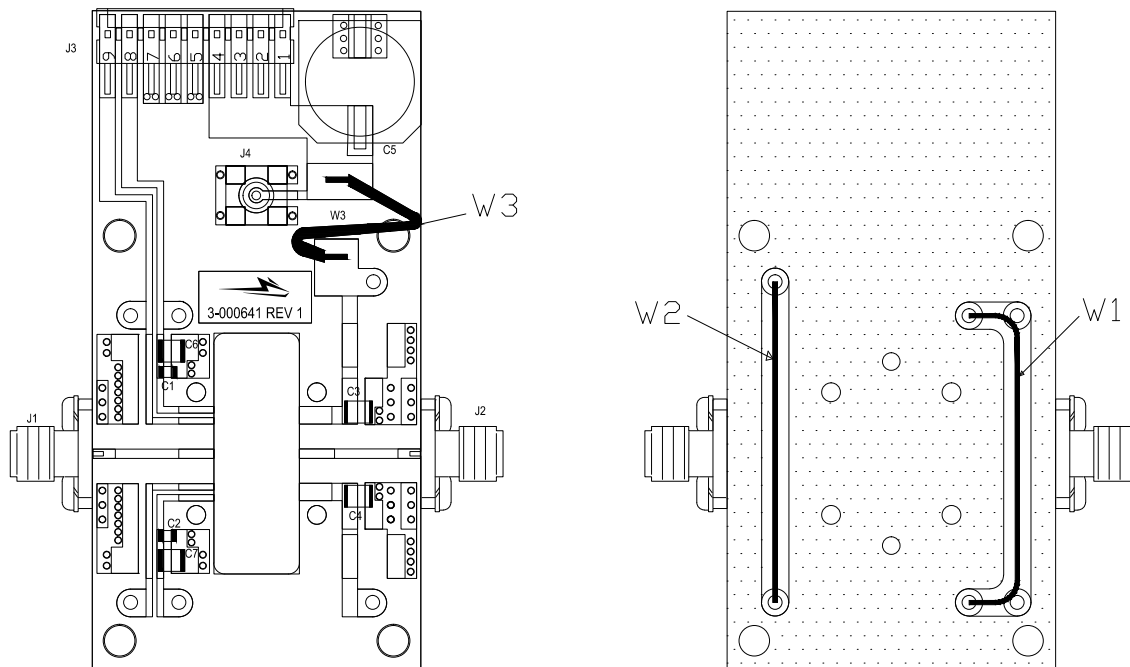




CMPA1D1E025F-AMP Demonstration Amplifier Circuit Schematic

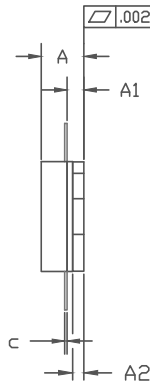
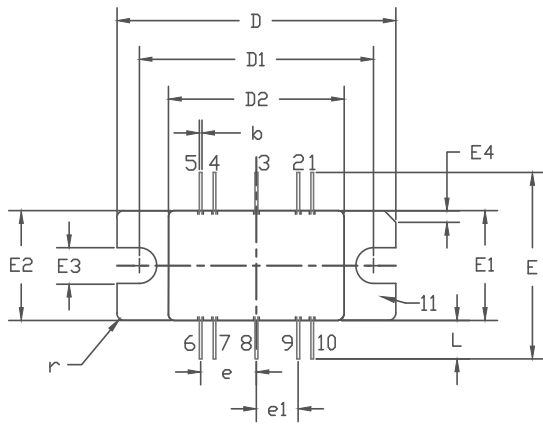


CMPA1D1E025F-AMP Demonstration Amplifier Circuit Outline





Product Dimensions CPM1D1E025F (Package Type – 440213)



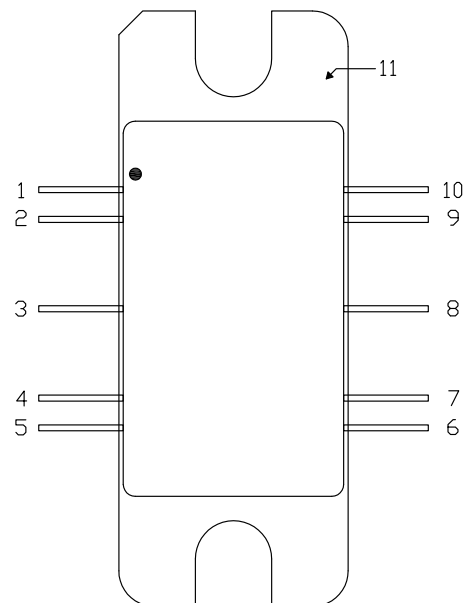
PIN 1: GATE BIAS 6: DRAIN BIAS
 2: GATE BIAS 7: DRAIN BIAS
 3: RF IN 8: RF OUT
 4: GATE BIAS 9: DRAIN BIAS
 5: GATE BIAS 10: DRAIN BIAS
 11: SOURCE

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

DIM	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.148	0.168	3.76	4.27	
A1	0.055	0.065	1.40	1.65	
A2	0.035	0.045	0.89	1.14	
b	0.01 TYP		0.254 TYP		10x
c	0.007	0.009	0.18	0.23	
D	0.995	1.005	25.27	25.53	
D1	0.835	0.845	21.21	21.46	
D2	0.623	0.637	15.82	16.18	
E	0.653 TYP		16.59 TYP		
E1	0.380	0.390	9.65	9.91	
E2	0.380	0.390	9.65	9.91	
E3	0.120	0.130	3.05	3.30	
E4	0.035	0.045	0.89	1.14	45° CHAMFER
e	0.200 TYP		5.08 TYP		4x
e1	0.150 TYP		3.81 TYP		4x
L	0.115	0.155	2.92	3.94	10x
r	0.025 TYP		.635 TYP		3x

Pin Number	Qty.
1	Gate Bias
2	NC
3	RF IN
4	NC
5	Gate Bias
6	Drain Bias
7	
8	RF OUT
9	Drain Bias
10	
11	Source





Part Number System

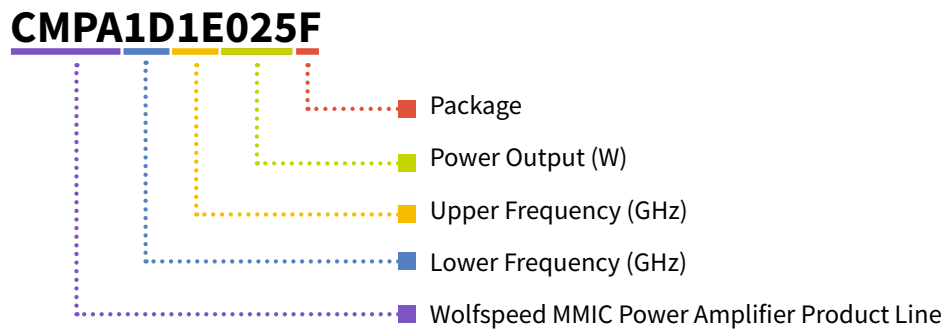


Table 1.

Parameter	Value	Units
Lower Frequency	13.75	GHz
Upper Frequency ¹	14.5	
Power Output	25	W
Package	Flange	—

Note:

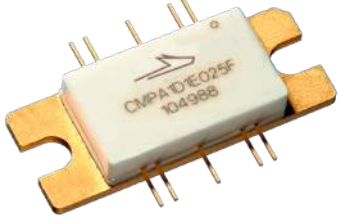

¹ Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Table 2.

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples	1A = 10.0 GHz 2H = 27.0 GHz



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CPA1D1E025F	GaN HEMT	Each	 A photograph of a small, rectangular, light-colored GaN HEMT component mounted on a gold-colored carrier. The component has several pins extending from its sides. The carrier is marked with the part number 'CPA1D1E025F' and the date '104988'.
CPA1D1E025F-AMP	Test board with GaN MMIC installed	Each	 A photograph of a blue printed circuit board (PCB) populated with various electronic components, including a central GaN MMIC, capacitors, and connectors. The board is shown from a top-down perspective.

**For more information, please contact:**

4600 Silicon Drive
Durham, NC 27703 USA
Tel: +1.919.313.5300
www.wolfspeed.com/RF

Sales Contact
RFSales@wolfspeed.com

RF Product Marketing Contact
RFMarketing@wolfspeed.com

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